

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Zhe Wang</td> <td>08/10/2012</td> </tr> <tr> <td>Qinglin Song</td> <td>08/10/2012</td> </tr> <tr> <td>Shengli Pang</td> <td>08/10/2012</td> </tr> <tr> <td>Fanghui Gu</td> <td>08/10/2012</td> </tr> </tbody> </table>		Name	Execution Date	Zhe Wang	08/10/2012	Qinglin Song	08/10/2012	Shengli Pang	08/10/2012	Fanghui Gu	08/10/2012
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Zhe Wang	08/10/2012										
Qinglin Song	08/10/2012										
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Fanghui Gu	08/10/2012										
RECEIVING PARTY DATA											
Name:	Goertek Inc.										
Street Address:	No. 268 DongFang Road, Hi-Tech Industry										
Internal Address:	Development District										
City:	WeiFang, Shandong 261031										
State/Country:	CHINA										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13581823</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13581823						
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Application Number:	13581823										
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Total Attachments: 2 source=237416.000008 ASSIGNMENT#page1.tif source=237416.000008 ASSIGNMENT#page2.tif											

CH \$40.00 13581823

ASSIGNMENT

WHEREAS WE, **Wang, Zhe; Song, Qinglin; Pang, Shengli; Gu, Fanghui**, [hereinafter referred to Assignors], have made an invention entitled: **A MEMS MICROPHONE AND METHOD FOR PACKAGING THE SAME**, for which we are the listed inventors for the application for United States Letters Patent referred to below as the Formal Application;

WHEREAS GOERTEK INC., whose mailing address is **No.268 DongFang Road, Hi-Tech Industry Development District WeiFang, Shandong 261031, P.R. China** (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the above-identified Formal Application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, we, as Assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, MY entire right, title, and interest in and to this invention, the above-identified patent application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patents which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY covenant that we have the full right to convey the interest assigned by this Assignment, and we have not executed and will not execute any agreement in conflict with this Assignment;

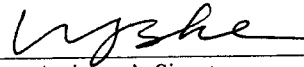
AND, WE HEREBY further covenant and agree that we will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to ME respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may by necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuing, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent prosecution for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns;

AND, WE HEREBY further covenant and agree that we will assign, and hereby do assign, to Assignee, its lawful successors and assigns, MY entire right, title, and interest in and to any and all patent applications, both United States and foreign, and all Letters Patent that may be granted thereon, that claim priority to this invention or to the above-identified provisional or non-provisional applications in any manner, such applications specifically including, but not limited to, divisionals, continuations, continuations-in-part, and all other provisional and non-provisional applications.

Assignor: **Wang, Zhe**

Address of Assignor:

206 Clementi Ave 6 #10-101, Singapore 120206(SG)



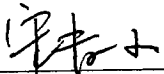
Assignors's Signature

Date:

Assignors: Song, Qinglin

Address of Assignor:

No.268 DongFang Road, Hi-Tech Industry Development District
WeiFang, Shandong 261031
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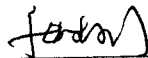
Assignors's Signature

Date: 2012.8.10

Assignor: Pang, Shengli

Address of Assignor:

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WeiFang, Shandong 261031
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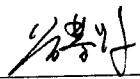
Assignors's Signature

Date: 2012.8.10

Assignor: Gu, Fanghui

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